

Corporate Explanatory Meeting Result of Mar. 2011

May.25th,2011
YAC Co., Ltd.



Program

- 1. Outline of the Company · · · · · · Takefumi Momose /Mr. President of YAC Co., Ltd.
- 3. Business Plan of year Mar. 2012 Takefumi Momose /Mr. (The 3rd Year of 10th 3 years Business Plan) President of YAC Co., Ltd.
- 4. Outline of Denko Co., Ltd.·····Tatsunori Fukuda /Mr.

 President of Denko Co., Ltd.
- 5. Q&A



1. Outline of the Company



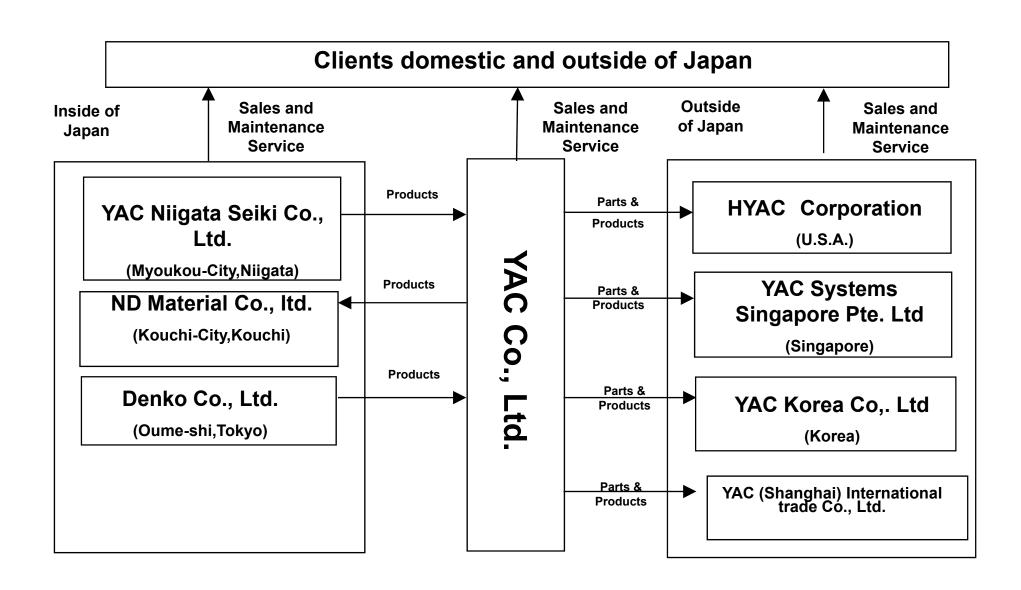
1-1 Basic Information

(2011年5月24日現在)

N a m e	YAC Co., Ltd.								
Local Code	6298 (Tokyo Stock exchange 1st Section)								
Established May,1973									
Representative	Takefumi Momose / Mr. President								
O f f i c e s	Head Office: 3-11-10, Musashino, Akishima-shi, Tokyo, Japan Branches: Osaka-City, Akishima-shi (Japan), Hshinchu (Taiwan) Factories: Akishima-shi, Yamanashi-City, Kumamoto-City, Oita-City								
A f f i l i a t e C o m p a n i e s	YAC Niigata Seiki Co., Ltd. (Myoukou-City, Niigata, Japan) HYAC Corporation (U.S.A.) YAC Systems Singapore Pte. Ltd. (Singapore) YAC KOREA CO., LTD. (Korea) YAC (Shanghai) International Trade Co., Ltd. (Peoples Republic of China) Denko Co., Ltd. (Oume-shi Tokyo, Japan)								
	ND Material Co., Ltd. Shinoda Plasma Co., Ltd.								
Paid up Capital	2,756 Million Yen								
	Developing, Manufacturing & Selling of Electronics Related Equipment and Cleaning System								
Account Closing	On March 31st								



1- 2 Functions of YAC and It's Affiliated Companies





1-3 Special Features of YAC Co., Ltd.

- (1) Business Diversified in 7 Fields.
- (2) Fables Management.
- (3) Challenging for M&A and Alliance.
- (4) Global Enterprise Focusing Asia.
- (5) All-in-one Management with Employee.
- (6)Strict Budget Control System.



Main Products

▲ Hard Disc Related Business

- Banishing Equipment
- Wiping Equipment
- UV Cure Equipment
- Clean Conveyer System

▲ Flat Panel Display Equipment

- Plasma Dry Etching System
- Plasma Dry Ashing System
- Anneal System

▲Semiconductor Equipment

•Test Handler for Logic IC

▲Photo Voltaic Equipment

- Texture Equipment, Diffusion,
- ISO/PSG System, AR Coating
- ▲ FEL Equipment
- Emitter for FEL and FEL Lump

▲Cleaning System

- Automatic bagging Machine
- Shirts Pressing Machine
- Apparel Machine

▲Heating equipment for

FPD,PV, and Precious Parts of

Electronics and Automobile



< Hard Disk Equipment Area >

Banisher	The disk surface precise polishing equipment to eliminate the nano-size projections on the disk surface after the process of magnetic film generating.
Wiping System	The equipment to remove particles on the disk surface and to equalize the lubricant agent after the process of magnetic film generating.
Clean Conveyer (for Hard Disk Factories)	The roller type clean conveyer system - Easier line designing by module concept - Higher transport efficiency than AGV or OHT by free loading and unloading as-needed.
Clean Conveyer (for Semiconductor , Solar cell Factories)	The roller type clean conveyer system - Larger width and higher load bearing & transporting speed are required Semiconductor: for 300mm wafer cassette transporting, - Solar cell :for Glass Substrate or 5inch wafer cassette transporting.
Clean Conveyer (for LCD Factories)	The roller type clean conveyer system - Larger width and higher load bearing & transporting speed are required for transporting Glass. substrate cutting by panel size.



Banisher



Clean Conveyer (for Hard Disk Factories)



Clean Conveyer (for Semiconductor Factories)



< LCD Equipment Area >

Plasma Dry Etching System

The equipment to generate the micro transistors which control the directions of liquid crystals in each cell.

After eliminating of the area except hardened area by exposure, this equipment eliminates the exposed thin film by using plasma.



G7 Plasma Dry Etching System (3-chamber type)

Applicable Glass **Substrate Sizes**

G2

G4 G4.5

G5

G5.5

G6

G7 G7.5

G8



< Semiconductor Equipment Area >

IC Test Handler (For Logic ICs)

The equipment to make automatic sorting based on the test result signal from the tester in the IC testing process.

It also makes high or low temperature testing environment (-55 deg.C to 155 deg.C) as the occasion demands.



IC Test Handler (4-IC Parallel Testing, Ambient Type)



=New Model= IC Test Handler (16-IC Parallel Testing)



< PV Equipment Area >

PV Process Equipment. Whole line for Single-crystal and Multi-crystalline type PV production

Texturing (batch in-line equipment)

■ Diffusion Furnace (P-coating equipment / tube (batch) type / in-line equipment)

PSG (ISO) (batch in-line equipment)

■ Antireflection Film Form (PE CVD equipment)

■ Circuit Printing (Screen print / Drying Oven)

■ Circuit Forming (BSF form) (Baking Furnace)

Other Related Equipments





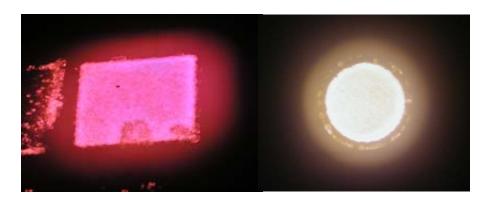


< FEL Equipment Area >

Manufacturing of Nano-Diamond Thin Film

The Electron Emitter using Nano-Diamond thin film for FEL (Field Emission Lamp) Features: (Lamp use for Nano-diamond thin film.)

- · Different as previous fluoresce light, non toxic substance like mercury / lead.
- · Very high energy and environmentally efficiency compare with a LED lamp.
- · Long-Life cycle Lamp compare with fluoresce light.
- · Less generate heat compare with fluoresce light and LED.
- · Flexible control of light wave length and color mixture.



radiation



Trial Product (Desk Lamp)



< Cleaning Equipment Area >

Shirt Pressing Machines (For Body)	The machine to press the body area of the shirt on the the dummy body by shutting in between 2 heat plates. (Options) Dual-Body Type, Single Body Type Auto Carry System. (The system to make automatic transferring to the hanger after finishing)
Pressing Machines (For Tuck & Sleeve)	The machine to press tuck & sleeve areas (Options) Dual type, Single Type.
Pressing Machines (For Collar & Cuffs)	The machine to press Collar & Cuffs areas (Options) Dual type, Single Type.
Bagging Machines	The machine to bag the finished items using plastic film cover. (Options) Hanger Type, Folder Type.
Apparel related Machines	Sponging Machine: to steam and press clothes for stability, Fusing Machine: to fuse clothes after cutting by parts, Pressing Machine: to press for smoothing down wrinkles.



Shirt Pressing Machine (For Body: Dual Type)



Bagging Machine (Hanger Type)



Sponging Machine (For Apparel)



Pressing Machine (For Apparel)



Precise Heating Treatment Equipment (Denko co., Ltd.>

Heating Equipment for Flat Panel Display (FTP)	Vertical Multistage Glass Heating Treatment Furnace Vertical Multistage Glass Anneal Furnace Walking Beam Type Consecutive Heating Treatment Furnace
PV Related Equipment	Vertical Glass Heating Furnace EVA Bridge Furnace for Thin Film Walking Beam Type Continuous Drying Furnace Vertical Multistage Diffusion Furnace
Heating Furnace for precision parts	Roller Hearth Consecutive Anneal Kiln Continuous Conveyer Muffle Kiln, Consecutive Conveyer Muffleless Kiln Testing Furnace
Heater and Other Related Equipment	Radiant Pat Heater(PD •GPD) Infrastructure Unit (BD •SG) Infrastructure Unit Heater (PS •PU •PH •PM),Other Industrial Heaters
Heater for Automobile	Sheet Steel Tempering Equipment, Molding Tempering equipment, Molding Preheating Equipment



TFT Alignment Layer Heating Treatment and Seal Drying Furnace



Continuous Conveyer Kiln



Unit Heater



2. Outline of Financial Result March 31st, 2011



- Recovery of Business like a Literature U.
- **■** Further Strengthened Corporate Structure.
- Tremendously Increased New Orders for Smartphone Parts and PV Equipment.
- A new Affiliate Company Joined.



2-2 Financial result (consolidated)

Million Yen

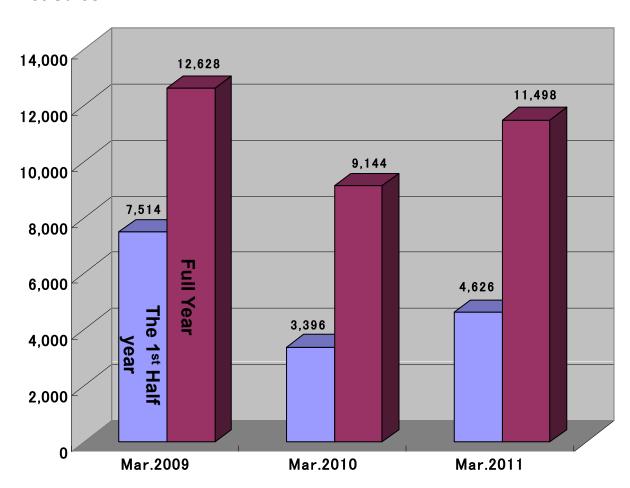
	Item	Ma	ar.2009	Ma	ar.2010	Ma	ar.2011	ge from Mar 2010 amount)	Chai	nge from Mar. 2010 (%)
Net S	ales		12,628		9,144		11,498	2,354		25.7%
	Memory Disk		2,238		1,062		2,611	1,549		145.9%
	Flat Panel		7,609		6,134		4,330	▲ 1,804		▲29.4%
	Semi Con.		1,164		475		1,257	782		164.6%
	PV		_		203		2,004	1,801		887.2%
	FEL		1		2		9	7		350%
	Cleaning		1,615		1,266		1,287	21		1.7%
Opera	ating Income		255		158		699	541		342.4%
Ordin	nary Income		430		104		726	622		598.1%
Net Ir	ncome		510		11		395	384		3,490.9%
Net in	come par share		54.88		1.27		42.59	41.32		
Operat	ting Income Ratio		2.0%		1.7%		6.1%	_		_
R&D	Expense		310		286		262	▲ 24	_	▲8.4%
Capit	al Expenditure		217		513		159	▲354		▲69.0%
Depre	eciation		183		295		250	▲ 45		▲15.3%



2-3 Movement of Annual Sales (consolidated)

Consolidated

Net Sales





2-4 New Order Received by Business Unit (Consolidated) Million Yen

ltem	Mar. 2009	Mar. 2010	Mar.2011	Change from Mar. 2010 (Amount)	Change from Mar.2010 (%)
Memory Disk Related Business	1,667	1,045	2,775	1,730	165.6%
Flat Panel Display Related Business	5,778	1,790	4,913	3,123	174.5%
Semiconductor Related Business	773	839	1,021	182	21.7%
Photovoltaic Related Business	_	948	1,965	1,017	107.3%
FEL Business	1	2	8	6	300.0%
Total	8,220	4,627	10,685	6,058	130.9%

Amount of new received order on Cleaning System Business is the same amount as the sales amount. Because that Business Unit takes Make to Stock manufacturing system.

2-5 Outstanding balance of order received by Business Unit (Consolidated) Million Yen

Items	Mar.2009	Mar.2010	Mar.2011	Change from Mar. 2010 (amount)	Outstanding Balance of orders received and unofficial notice
Memory Disk Unit	291	275	439	164	1,177
Flat Panel Dis. Unit	7,097	1,178	1,761	583	10,185
Semiconductor Unit	10	375	139	▲236	290
PV Unit	1	745	706	▲39	893
FEL Unit	0	0	0	_	_
Denko Co., Ltd.	_	_	_	_	2,127
Total	7,399	2,574	3,047	473	14,672



Items	Mar. 2009	Mar. 2010	Mar. 2011	Change from Mar. 2010 (amount)
Current Assets	13,607	14,076	14,761	685
Cash & Cash Equivalent	5,351	5,232	6,538	1,305
Account Receivables	4,647	6,770	5,775	▲994
Inventories	2,994	1,682	2,185	502
Others	613	390	262	▲ 127
Fixed Assets	3,357	3,616	3,681	64
Tangible Fixed Assets	2,842	3,030	2,916	▲ 114
Intangible Fixed Assets	88	100	▲ 96	▲3
Investments & Others	426	484	668	183
Total Assets	16,965	17,692	18,442	750
Current Liabilities	3,513	4,891	5,206	315
Account Payables	2,443	3,004	3,658	653
Short Term Borrowings	611	638	687	48
Others	459	1,248	861	▲386
Fixed Liabilities	2,654	2,091	2,337	245
Bond & Long Term Borrowings	2,128	1,560	1,772	212
Others	525	531	564	33
Total Liabilities	6,167	6,983	7,544	560
Net Assets	10,797	10,708	10,898	189
Total Liabilities & Net Asset	16,965	17,692	18,442	750



2-7 Summary of Cash Flow Statement (Consolidated)

Million Yen

Items	Mar. 2009	Mar. 2010	Mar. 2011
Cash Flow from Operating Activities	3,568	330	1,845
Cash Flow from Investing Activities	▲11	▲ 454	▲222
Cash Flow from Financing Activities	▲ 2,814	11	▲ 286
Cash and Cash Equivalent at the End of the Term	5,344	5,216	6,520



3. Business Plan for Year 2012

(The 3rd Year of the 10th middle Term Business Plan)



3-1 Guidelines of Business Activities for Year 2012

(1) 5 Top Priority Points for Year 2012

- **1**To increase the sales of smart phone related equipment.
- 2 To expand the size and to make profit, in PV business.
- ③ To strengthen the synthetic total group power of YAC.
- **4** To indicate when FEL business is commercialize.
- **⑤** To strengthen further profitable corporate body.
 - Strict Budget Control System.
 - KCS30 Campaign.



(2) Atmosphere surrounding YAC and Main Target

<Hard Disk Market>

- To achieve 100% of market share in banisher business by newly developed high throughput product.
- To achieve 100 % of market share in UV cure business.
- To increase the sales by selling clean conveyer system and expandable goods for new clients.

<Flat Panel Display Market>

• Market share of plasma dry etching system and anneal system will be increased by the growth of smart phone and tablet PC market.

Semiconductor Business Market>

- To increase the main client.
- To get new clients in power semiconductor business.



<PV Equipment Market>

- To get new clients in Taiwan and China other than Japan and Korea.
- To develop CVD and diffusion furnace for crystalline silicon.

<Cleaning System Business>

- To cultivate the overseas market like China.
- To start to manufacture outside of Japan.

<FEL Business>

• To indicate the time of commercialization in FEL business.



3−2 Plan for Year 2012 (Consolidated)

Million Yen

Items	Mar. 2009	Mar. 2010	Mar. 2011	Mar. 2012 (forecast)		Forecasted Changes from Mar.2011 (amount)	Forecasted Changes from Mar.2011 (%)
				The First Half Year	Full Year		
Net Sales	12,628	9,144	11,498	7,000	19,000	7,502	65.2%
Operating Profit	255	158	699	400	1,650	951	136.1%
Ordinary income	430	104	726	380	1,600	874	120.4%
Net Profit	510	11	395	200	900	505	127.8%
Earning par Share (Yen)	54.88	1.27	42.59	21.51	96.80	54.21	_



3-3 Sales by Business Unit (Consolidated)

Million Yen

Business Unit	Mar. 2009	Mar. 2010	2011年 3月期	Mar. 2012 (forecast)		Forecasted Changes from Mar.2011 (amount)	Forecasted Changes from Mar.2011 (%)
				The First Half Year	Full Year		
Memory Disk	2,238	1,062	2,611	1,600	3,400	789	30.2%
Flat Panel display	7,609	6,134	4,330	1,900	7,500	3,170	73.2%
Semiconductor	1,164	475	1,257	400	1,000	▲257	▲20.4%
PV	_	203	2,004	800	2,800	796	39.7%
FEL	1	2	9	0	0	_	_
Cleaning System	1,615	1,266	1,287	500	1,300	13	1.0%
Denko Co., Ltd.	_	_	-	1,800	3,000		_
Total	12,628	9,144	11,498	7,000	19,000	7,502	65.2%



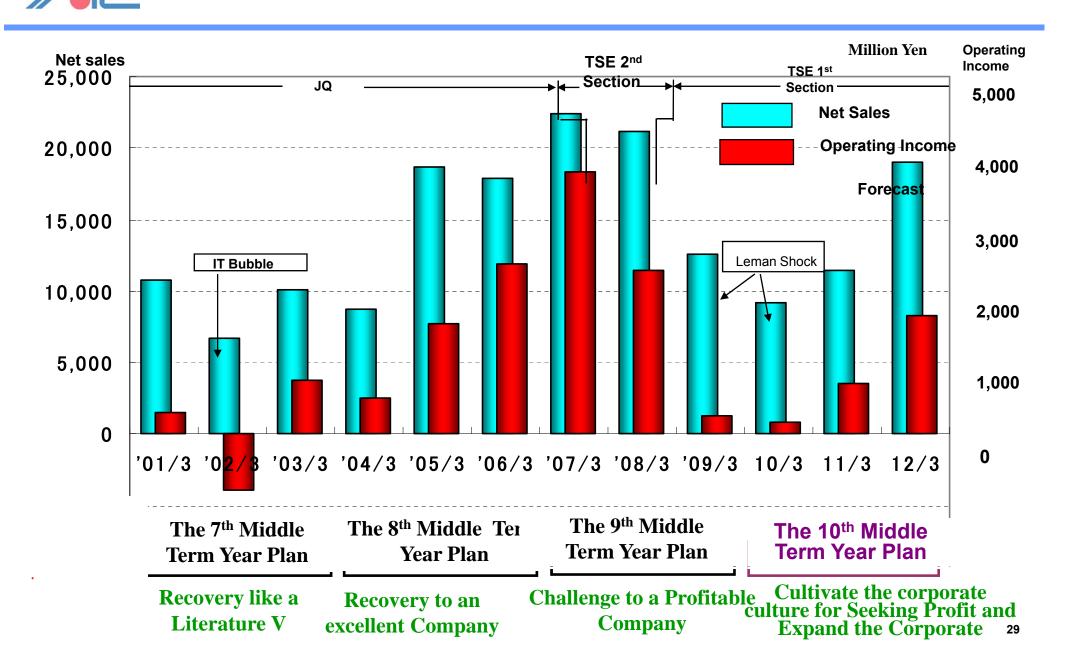
3-4 Previous Year Results

Ordinary Number in Company Age	Financial Year	Net Sales	Operating Income	
The 1st year	May,1974	43	1	
The 5 th year	May,1978	220	12	
The 10 th year	May,1983	725	49	
The 15 th year	May,1988	1,692	101	
The 20 th year	May,1993	4,467	369	
The 25 th year	Mar.,1998	7,508	645	
The 30 th year	Mar.,2003	10,055	766	
The 35 th year	Mar.,2008	21,198	2,295	
The 39 th year	Mar.,2012	19,000	1,650	

- consolidated



-5Movement of Financial Result vs. The 10th Middle Term Year Plan (Consolidated)





4 Challenge for further growth

4-1 Scenario for Billionaire Company

100 million yen

	3 rd Year of the 10 th Plan	The 11 th Middle Term Year Plan			The 12 th Middle Term Year Plan	
	Mar.2012	Mar.2013	Mar.2014	Mar.2015	Mar.2016	Mar.2017
Old Business	132	To Be Released on Nov.2011				250
PV	28					250
FEL						300
New Business by M&A	30					200
Total	190					1,000



4-2 Basic Strategy for Billionaire Company

<1>Expanshon of Present Business

- 1)To increase the market share by differentiation.
- ②To increase the sort of products by self developing as well as acquisitions.
- To expand the maintenance business and the sales of expendable goods.
- 4)To expand the business globally further.

(2) To Enter into The New Business

- 1)Successful launch of FEL.
- ②To develop new products by ourselves (CVD, Diffusion Furness for PV).
- (3) Alliance like a M&A.

(3) To Promote the campaign for Profitable Corporate Culture

- 1)To Establish the Perfect Strict Budget Control System.
- ②To Complete the KCS30 Campaign throughout the YAC Group.
- (4) To Strengthen the Human Power in Management Team.
- (5)To further comply with Law and Regulations.
- * The 11th middle term year plan (2012~2014) will be established during the 1st half of this year.



The prospects described in this document is based on the information we have as of the time this document is published, and the actual result may differ from such prospects due to various unexpected factors.

YAC Co., Ltd.